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REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A		17 JUL 24	X

D

D

C

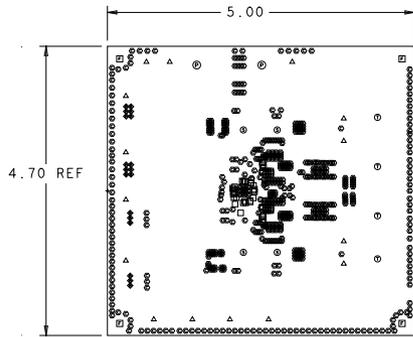
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HOLE TOLERANCE
 UNLESS SPECIFIED
 PLATED: +/- 3 MILS
 NON PLATED: +/- 2 MIL

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	PLATED	QTY	TOLERANCE/NOTES
□	6.0	PLATED	66	
•	9.99	PLATED	551	
◆	40.0	PLATED	18	
△	100.0	PLATED	15	
⊙	191.0	PLATED	2	
⊗	213.0	PLATED	4	
⊕	118.0	NON-PLATED	4	
⊖	185.0	NON-PLATED	4	

TOTAL HOLES: 664

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES	APPROVAL BILLY PHILLIPS 19AUG20	DATE 19AUG20			
DESIGNED BY BOB MACDONALD 19AUG20	DESIGNED BY DAVE WILLIAMS 19AUG20	DESIGNED BY ADDT LIBRARY 19AUG20			TITLE FABRICATION EVAL-LTC7892-BZ
MATERIAL	FINISH RACHA L. 29JUN22	SIZE D	FSCM NO 2435509	DRAWING NUMBER -074836	REV A
DO NOT SCALE DWG	SCALE 1/1	SHEET 1 OF 2			

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REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A		17 JUL 24	X

NOTES : UNLESS OTHERWISE SPECIFIED

- DIMENSIONS ARE IN INCHES (EXCEPT WHERE NOTED). ALL DOCUMENTS & SPECIFICATIONS REFERRED TO BELOW SHOULD BE THE LATEST REVISIONS.
- BOARD MATERIAL (USE CHECKED ITEMS)

MATERIAL : HOMOGENOUS MATERIALS IN THIS BOARD SHALL BE COMPLAINT WITH THE EU DIRECTIVE 2002/95/EC

 - (X) ISOLA 370HR OR S1000-2 OR IT180 OR EQUIVALENT
 - () ISOLA-FR408HR OR EQUIVALENT
 - () ISOLA 15410
 - () MEGTRON 6
 - () NEMCO-4000-13
 - () ROGERS 4350B
 - () ROGERS 3003
 - () ARLON 85N
 - () EN330D
 - () OTHER _____
- ALL LAMINATES & BONDING MATERIALS SHOULD BE SELECTED FROM IPC-4101 OR IPC-4103. (TG>170 DEG TD>300 DEG) UL FLAMMABILITY RATING 94V-0. BOARD MATERIAL & CONSTRUCTION SHALL MEET THE REQUIREMENTS OF UL796/UL796F.
- REFER TO IPC-6010 SERIES, CLASS 2 FOR FABRICATION. WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2.
- REFER TO LAMINATION DIAGRAM FOR OVERALL BOARD THICKNESS, TOLERANCE APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES. FINISHED THICKNESS MEASURED FROM TOP COPPER TO BOTTOM COPPER.
- BOW & TWIST NOT TO EXCEED 0.0075 INCHES (0.75%) PER LINEAR INCH AND SHOULD BE MEASURED PER IPC-TM-650, METHOD 2.4.22.
- ACCEPTABILITY PER ADI SPECIFICATION TST00115.

TOOLING :

- IMPEDANCE REQUIREMENTS: IF NO STACKUP IS DEFINED, THE VENDOR IS ALLOWED TO ADJUST THE DIELECTRIC THICKNESS & TRACE WIDTHS TO MEET THE IMPEDANCE REQUIREMENT. IF SPECIFIED, THE VENDOR MUST MEET THE REQUIREMENTS LISTED IN THE IMPEDANCE TABLE. ANY ADJUSTMENT MADE TO THE DEFINED STACKUP, TRACE WIDTH & SPACING THAT IMPACT THE REQUIREMENTS MUST HAVE WRITTEN APPROVAL FROM ADI.
- FILLET OPTIONS TO ENHANCE RELIABILITY AT PAD JUNCTIONS WHERE SPACING PERMITS.
 - () FILLETS ALLOWED
 - (X) FILLETS NOT ALLOWED
- THIEVING:
 - () VENDOR MAY ADD THIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS MAINTAINING A MINIMUM 0.100 INCH CLEARANCE FROM ALL COPPER FEATURES.
 - (X) VENDOR MAY NOT ADD THIEVING TO COMPENSATE FOR LOW COPPER DENSITY AREAS.
- LAYER TO LAYER REGISTRATION SHALL BE WITHIN 0.003 INCHES.

FINISH :

- DRILL SIZES ARE FINISHED HOLE SIZES. ALL HOLES SHALL BE LOCATED WITHIN 0.005 INCHES DTP UNLESS SPECIFIED. MINIMUM BARREL PLATING OF 0.001 INCHES. PLATED HOLES SHALL NOT BE ROUGH OR IRREGULAR SO AS TO HINDER PROPER SOLDER WICKING. BARREL RELIEF ON SOLDERMASK ALLOWED IN UNFILLED VIA IN PAD HOLES.
- PLATING SPECIFICATION:
 - (X) REFER TO LAMINATION DIAGRAM FOR FINISHED COPPER WEIGHT/THICKNESS REQUIREMENTS
 - THE STARTING COPPER WEIGHT/THICKNESS CAN VARY AS LONG AS THE FINISHED COPPER WEIGHT/THICKNESS IS NOT LESS THAN THE SPECIFIED VALUE.
- SURFACE FINISH:
 - (X) IMMERSION GOLD (ENIG) 1.58-3.84 MICRO INCHES OVER 118-236 MICRO INCHES MIN. OF ELECTROLESS NICKEL PER IPC-4552
 - () OSP (ORGANIC SOLDERABILITY PRESERVATIVE)
 - () IMMERSION SILVER
 - () SOFT WIRE BONDABLE GOLD 30-50 MICRO INCHES OF SOFT WIRE
 - BONDABLE GOLD OVER 100-150 MICRO INCHES OF NICKEL
 - () EDGE CONNECTOR FINGERS ARE TO BE PLATED WITH 100 MICRO-INCHES (.0001") OF LOW STRESS NICKEL UNDER 30 MICRO-INCHES (.0003") OF GOLD.
 - () OTHER _____
- SOLDERMASK:
 - SOLDERMASK OVER BARE COPPER OR BARE GOLD (BOTH SIDES) TO MEET IPC-SM-840.
 - IF PRESENT, DO NOT MODIFY SOLDERMASK DEFINED PADS (MASK OPENINGS LESS THAN COPPER PAD) WITHOUT APPROVAL.
 - (X) LPI
 - () OTHER _____
- COLOR
 - (X) GREEN
 - () OTHER _____
- APPLY SILKSCREEN TO BOTH SIDES USING A NON-CONDUCTIVE, EPOXY BASED INK PER ARTWORK.
 - (X) WHITE
 - () OTHER _____

TESTING :

- FINAL ELECTRICAL TEST TO BE PERFORMED USING PROVIDED IPC-D-356A NETLIST OR ODB++ FORMAT FILE. THE PCB SHALL HAVE A VERIFICATION STAMP.
- A TIME DOMAIN REFLECTOMETER REPORT (TDR) FOR EACH IMPEDANCE CONTROLLED LAYER & A CERTIFICATE OF COMPLIANCE SHALL BE PROVIDED BY VENDOR AT TIME OF SHIPMENT. INSTANCES WHERE TDR TESTING CAN'T BE PERFORMED BECAUSE THE TRACE LENGTH IS TOO SHORT ON THE OUTER LAYERS AT THE PIN ESCAPES IS ACCEPTABLE. ALL OTHER INSTANCES MUST BE REPORTED.
- MISCELLANEOUS :
 - IF PRESENT, ALL BLIND/BURIED VIAS WITH AN ASPECT RATIO <1:1 TO BE PLATED SHUT WITH COPPER WHEN USED AS VIA-IN-PAD OR AS A STACKED VIA. BLIND/BURIED VIAS WITH AN ASPECT RATIO >1:1 TO BE FILLED WITH NON-CONDUCTIVE EPOXY.
 - FOR VIA FILL INFORMATION REFER TO DRILL CHART:
 - (X) NON-CONDUCTIVE EPOXY FILL ALL LESS THAN 0.010 INCHES DRILLED VIAS
 - () COPPER FILL ALL 0.010 INCHES DRILLED VIAS
 - INTENTIONAL SHORTS:
 - IF AN INTENTIONAL SHORT REPORT IS SUPPLIED AND DOES NOT MATCH THE FAB DATA THEN ADI APPROVAL IS REQUIRED.
 - PENNETS:
 - () PENNETS TO BE INSTALLED BY FABRICATOR
 - () PENNETS NOT TO BE INSTALLED BY FABRICATOR
 - (X) NOT APPLICABLE
 - MANUFACTURER TO ETCH/STAMP WITH PERMANENT NON-CONDUCTIVE INK ON SECONDARY SIDE UNLESS OTHERWISE SPECIFIED:
 - A. UL CODE-FLAMMABILITY RATING FOR THOSE APPROVED MATERIALS(IF APPLICABLE)
 - B. DATE CODE
 - C. LOT NUMBER
 - D. MANUFACTURER LOGO
 - PANELIZATION:
 - BOARDS TO BE SHIPPED IN ARRAY AND KEPT INTACT
 - PANEL TO BE SUBJECTED TO CUSTOMERS APPROVAL
 - PANEL SOLDER PASTE STENCIL GERBER TO BE PROVIDED TO ANALOG
 - MINIMUM DESIGN LINE WIDTH IS .008 INCH.
 - MINIMUM DESIGN LINE SPACING IS .006 INCH.

FOR NOTES REFERENCE, SEE NUMBER 0022

LAMINATION DIAGRAM				
LAYER NUMBER	LAYER NAME	COPPER THICKNESS (OZ, INCH)	DIELECTRIC THICKNESS (INCH)	MATERIALS
1	TOP	2 OZ, 0.0028"		FINAL CU(THICKNESS AFTER PLATING)
			0.006	ISOLA 370HR/EQUIVALENT
2	LAYER_2	2 OZ, 0.0028"		CU CLAD
			0.010	ISOLA 370HR/EQUIVALENT
3	LAYER_3	2 OZ, 0.0028"		CU CLAD
			THINS AS REQ'D	ISOLA 370HR/EQUIVALENT
4	LAYER_4	2 OZ, 0.0028"		CU CLAD
			0.010	ISOLA 370HR/EQUIVALENT
5	LAYER_5	2 OZ, 0.0028"		CU CLAD
			0.006	ISOLA 370HR/EQUIVALENT
6	BOTTOM	2 OZ, 0.0028"		FINAL CU(THICKNESS AFTER PLATING)

THE FINISHED PCB THICKNESS TO BE: 0.062" +/-10%

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES	APPROVAL	DATE	
DESIGNED BY: BOB MACDONALD	BILLY PHILLIPS	19AUG20	
DRAWN BY: BOB MACDONALD	BOB MACDONALD	19AUG20	TITLE FABRICATION EVAL-LTC7892-BZ
CHECKED BY: DAVE WILLIAMS	DAVE WILLIAMS	19AUG20	
MATERIAL	ADDT LIBRARY	19AUG20	SIZE D 2435509 -074836
FINISH	ROCHELL	29JUN22	
DO NOT SCALE DWG	SCALE	1/1	REV A